

## 74LCX244

### Low Voltage Buffer/Line Driver with 5V Tolerant Inputs and Outputs

#### General Description

The LCX244 contains eight non-inverting buffers with 3-STATE outputs. The device may be employed as a memory address driver, clock driver and bus-oriented transmitter/receiver. The LCX244 is designed for low voltage (2.5V or 3.3V)  $V_{CC}$  applications with capability of interfacing to a 5V signal environment.

The LCX244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

#### Features

- 5V tolerant inputs and outputs
- 2.3V to 3.6V  $V_{CC}$  specifications provided
- 6.5 ns  $t_{PD}$  max ( $V_{CC} = 3.3V$ ), 10  $\mu A$   $I_{CC}$  max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- $\pm 24$  mA output drive ( $V_{CC} = 3.0V$ )
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:  
Human body model > 2000V  
Machine model > 200V
- Leadless DQFN Pb-Free package

**Note 1:** To ensure the high-impedance state during power up or down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

#### Ordering Code:

Order Number	Package Number	Package Description
74LCX244WM (Note 2)	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LCX244WMX_NL (Note 4)	M20B	Pb-Free 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LCX244SJ (Note 2)	M20D	Pb-Free 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX244BQX (Note 3)	MLP020B	Pb-Free 20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm
74LCX244MSA (Note 2)	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74LCX244MTC (Note 2)	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74LCX244MTC_NL (Note 4)	MTC20	Pb-Free 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74LCX244MTCX_NL (Note 4)	MTC20	Pb-Free 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

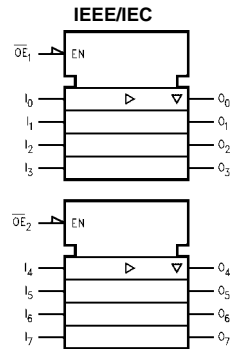
Pb-Free package per JEDEC J-STD-020B.

**Note 2:** Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

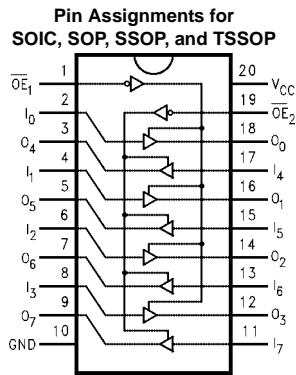
**Note 3:** DQFN package available in Tape and Reel only.

**Note 4:** "\_NL" indicates Pb-Free package (per JEDEC J-STD-020B). Please use order number as indicated.

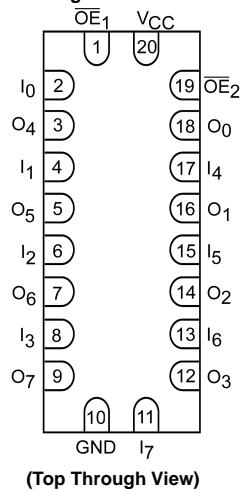
## Logic Symbol



## Connection Diagrams



### Pad Assignments for DQFN



## Pin Descriptions

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs
$I_0 - I_7$	Inputs
$O_0 - O_7$	Outputs

## Truth Tables

Inputs		Outputs (Pins 12, 14, 16, 18)
$\overline{OE}_1$	$I_n$	
L	L	L
L	H	H
H	X	Z

Inputs		Outputs (Pins 3, 5, 7, 9)
$\overline{OE}_2$	$I_n$	
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level  
L = LOW Voltage Level  
X = Immaterial  
Z = High Impedance

Absolute Maximum Ratings <sup>(Note 5)</sup>				
Symbol	Parameter	Value	Conditions	Units
V <sub>CC</sub>	Supply Voltage	−0.5 to +7.0		V
V <sub>I</sub>	DC Input Voltage	−0.5 to +7.0		V
V <sub>O</sub>	DC Output Voltage	−0.5 to +7.0 −0.5 to V <sub>CC</sub> + 0.5	Output in 3-STATE Output in HIGH or LOW State (Note 6)	V
I <sub>IK</sub>	DC Input Diode Current	−50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	−50 +50	V <sub>O</sub> < GND V <sub>O</sub> > V <sub>CC</sub>	mA
I <sub>O</sub>	DC Output Source/Sink Current	±50		mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature	−65 to +150		°C

### Recommended Operating Conditions <sup>(Note 7)</sup>

Symbol	Parameter	Min	Max	Units	
V <sub>CC</sub>	Supply Voltage	Operating Data Retention	2.0 1.5	3.6 3.6	V
	V <sub>I</sub>	Input Voltage	0	5.5	V
V <sub>O</sub>	Output Voltage	HIGH or LOW State 3-STATE	0 0	V <sub>CC</sub> 5.5	V
	I <sub>OH</sub> /I <sub>OL</sub>	Output Current	V <sub>CC</sub> = 3.0V to 3.6V V <sub>CC</sub> = 2.7V to 3.0V V <sub>CC</sub> = 2.3V to 2.7V	±24 ±12 ±8	mA
T <sub>A</sub>	Free-Air Operating Temperature	−40	85	°C	
Δt/ΔV	Input Edge Rate, V <sub>IN</sub> = 0.8V to 2.0V, V <sub>CC</sub> = 3.0V	0	10	ns/V	

**Note 5:** The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The “Recommended Operating Conditions” table will define the conditions for actual device operation.

**Note 6:** I<sub>O</sub> Absolute Maximum Rating must be observed.

**Note 7:** Unused inputs or I/Os must be held HIGH or LOW. They may not float.

### DC Electrical Characteristics

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = −40°C to +85°C		Units
				Min	Max	
V <sub>IH</sub>	HIGH Level Input Voltage		2.3 to 2.7 2.7 to 3.6	1.7 2.0		V
V <sub>IL</sub>	LOW Level Input Voltage		2.3 to 2.7 2.7 to 3.6		0.7 0.8	V
V <sub>OH</sub>	HIGH Level Output Voltage	I <sub>OH</sub> = −100 μA	2.3 to 3.6	V <sub>CC</sub> − 0.2		V
		I <sub>OH</sub> = −8 mA	2.3	1.8		
		I <sub>OH</sub> = −12 mA	2.7	2.2		
		I <sub>OH</sub> = −18 mA	3.0	2.4		
		I <sub>OH</sub> = −24 mA	3.0	2.2		
V <sub>OL</sub>	LOW Level Output Voltage	I <sub>OL</sub> = 100 μA	2.3 to 3.6		0.2	V
		I <sub>OL</sub> = 8 mA	2.3		0.6	
		I <sub>OL</sub> = 12 mA	2.7		0.4	
		I <sub>OL</sub> = 16 mA	3.0		0.4	
		I <sub>OL</sub> = 24 mA	3.0		0.55	
I <sub>I</sub>	Input Leakage Current	0 ≤ V <sub>I</sub> ≤ 5.5V	2.3 to 3.6		±5.0	μA
I <sub>OZ</sub>	3-STATE Output Leakage	0 ≤ V <sub>O</sub> ≤ 5.5V V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	2.3 to 3.6		±5.0	μA
I <sub>OFF</sub>	Power-Off Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 5.5V	0		10	μA

## DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = -40°C to +85°C		Units
				Min	Max	
I <sub>CC</sub>	Quiescent Supply Current	V <sub>I</sub> = V <sub>CC</sub> or GND	2.3 – 3.6		10	μA
		3.6V ≤ V <sub>I</sub> , V <sub>O</sub> ≤ 5.5V (Note 8)	2.3 – 3.6		±10	
ΔI <sub>CC</sub>	Increase in I <sub>CC</sub> per Input	V <sub>IH</sub> = V <sub>CC</sub> - 0.6V	2.3 – 3.6		500	μA

**Note 8:** Outputs disabled or 3-STATE only.

## AC Electrical Characteristics

Symbol	Parameter	T <sub>A</sub> = -40°C to +85°C, R <sub>L</sub> = 500Ω						Units
		V <sub>CC</sub> = 3.3V ± 0.3V		V <sub>CC</sub> = 2.7V		V <sub>CC</sub> = 2.5V ± 0.2		
		C <sub>L</sub> = 50 pF		C <sub>L</sub> = 50 pF		C <sub>L</sub> = 30 pF		
		Min	Max	Min	Max	Min	Max	
t <sub>PHL</sub>	Propagation Delay	1.5	6.5	1.5	7.5	1.5	7.8	ns
t <sub>PLH</sub>	Data to Output	1.5	6.5	1.5	7.5	1.5	7.8	
t <sub>PZL</sub>	Output Enable Time	1.5	8.0	1.5	9.0	1.5	10.0	ns
t <sub>PZH</sub>		1.5	8.0	1.5	9.0	1.5	10.0	
t <sub>PLZ</sub>	Output Disable Time	1.5	7.0	1.5	8.0	1.5	8.4	ns
t <sub>PHZ</sub>		1.5	7.0	1.5	8.0	1.5	8.4	
t <sub>OSHL</sub>	Output to Output Skew (Note 9)		1.0					ns
t <sub>OSLH</sub>			1.0					

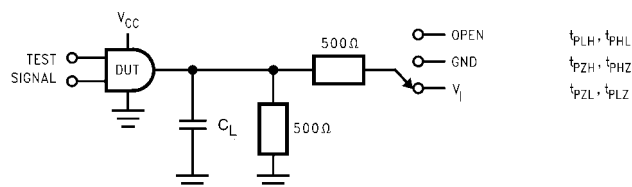
**Note 9:** Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>).

## Dynamic Switching Characteristics

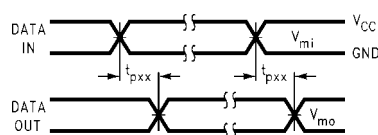
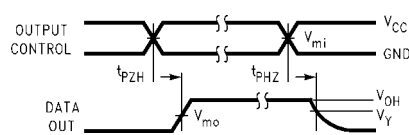
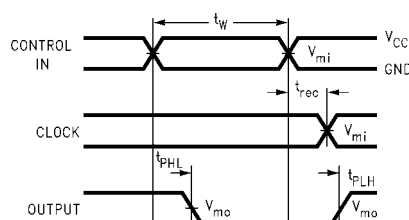
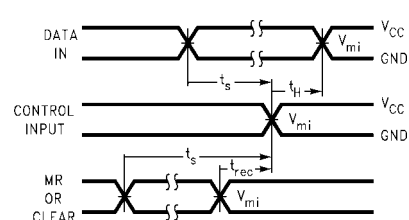
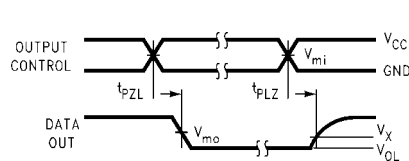
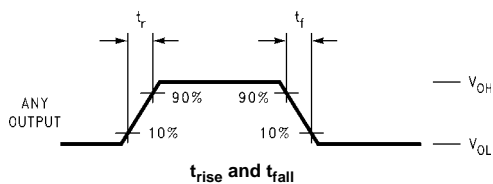
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C	Units
				Typical	
V <sub>OLP</sub>	Quiet Output Dynamic Peak V <sub>OL</sub>	C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3V, V <sub>IL</sub> = 0V C <sub>L</sub> = 30 pF, V <sub>IH</sub> = 2.5V, V <sub>IL</sub> = 0V	3.3 2.5	0.8 0.6	V
V <sub>OLV</sub>	Quiet Output Dynamic Valley V <sub>OL</sub>	C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3V, V <sub>IL</sub> = 0V C <sub>L</sub> = 30 pF, V <sub>IH</sub> = 2.5V, V <sub>IL</sub> = 0V	3.3 2.5	-0.8 -0.6	V

## Capacitance

Symbol	Parameter	Conditions	Typical	Units
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = Open, V <sub>I</sub> = 0V or V <sub>CC</sub>	7.0	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>CC</sub> = 3.3V, V <sub>I</sub> = 0V or V <sub>CC</sub>	8.0	pF
C <sub>PD</sub>	Power Dissipation Capacitance	V <sub>CC</sub> = 3.3V, V <sub>I</sub> = 0V or V <sub>CC</sub> , f = 10 MHz	25.0	pF

**AC LOADING and WAVEFORMS** Generic for LCX Family**FIGURE 1. AC Test Circuit ( $C_L$  includes probe and jig capacitance)**

Test	Switch
$t_{PLH}$ , $t_{PHL}$	Open
$t_{PZL}$ , $t_{PLZ}$	6V at $V_{CC} = 3.3V \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5V \pm 0.2V$
$t_{PZH}$ , $t_{PHZ}$	GND

**Waveform for Inverting and Non-Inverting Functions****3-STATE Output High Enable and Disable Times for Logic****Propagation Delay, Pulse Width and  $t_{rec}$  Waveforms****Setup Time, Hold Time and Recovery Time for Logic****3-STATE Output Low Enable and Disable Times for Logic****FIGURE 2. Waveforms  
(Input Characteristics;  $f = 1\text{MHz}$ ,  $t_r = t_f = 3\text{ns}$ )**

Symbol	$V_{CC}$		
	$3.3V \pm 0.3V$	$2.7V$	$2.5V \pm 0.2V$
$V_{mi}$	1.5V	1.5V	$V_{CC}/2$
$V_{mo}$	1.5V	1.5V	$V_{CC}/2$
$V_X$	$V_{OL} + 0.3V$	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$
$V_Y$	$V_{OH} - 0.3V$	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$

# Schematic Diagram Generic for LCX Family

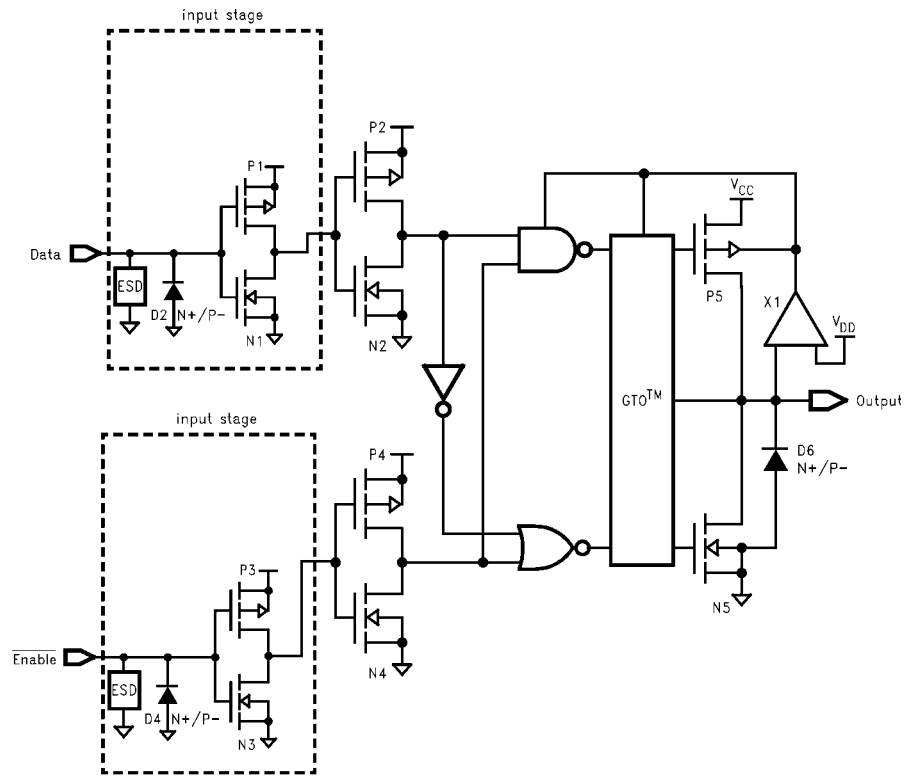


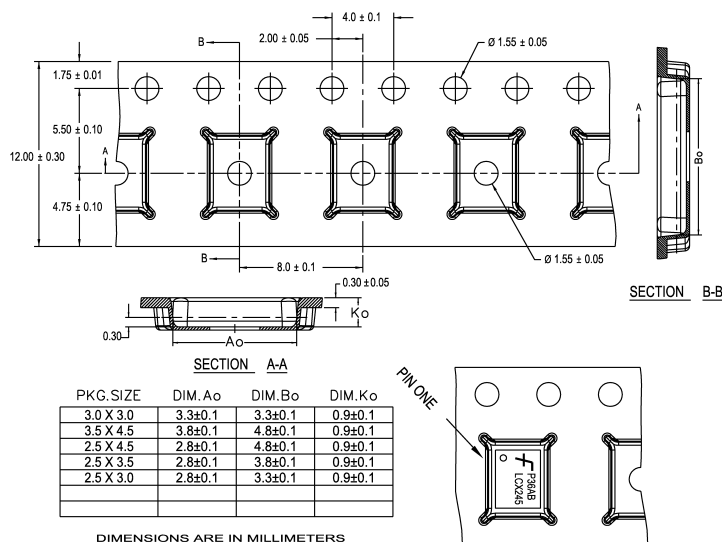
FIGURE 3.

## Tape and Reel Specification

### Tape Format for DQFN

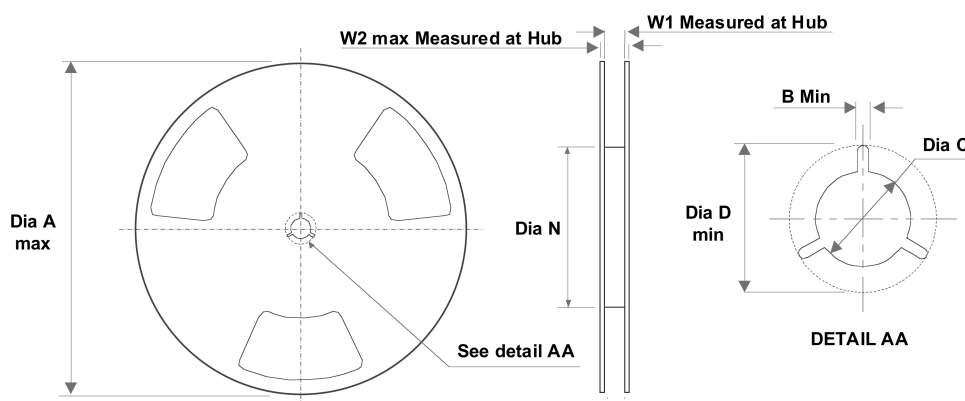
Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
BQX	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

### TAPE DIMENSIONS inches (millimeters)



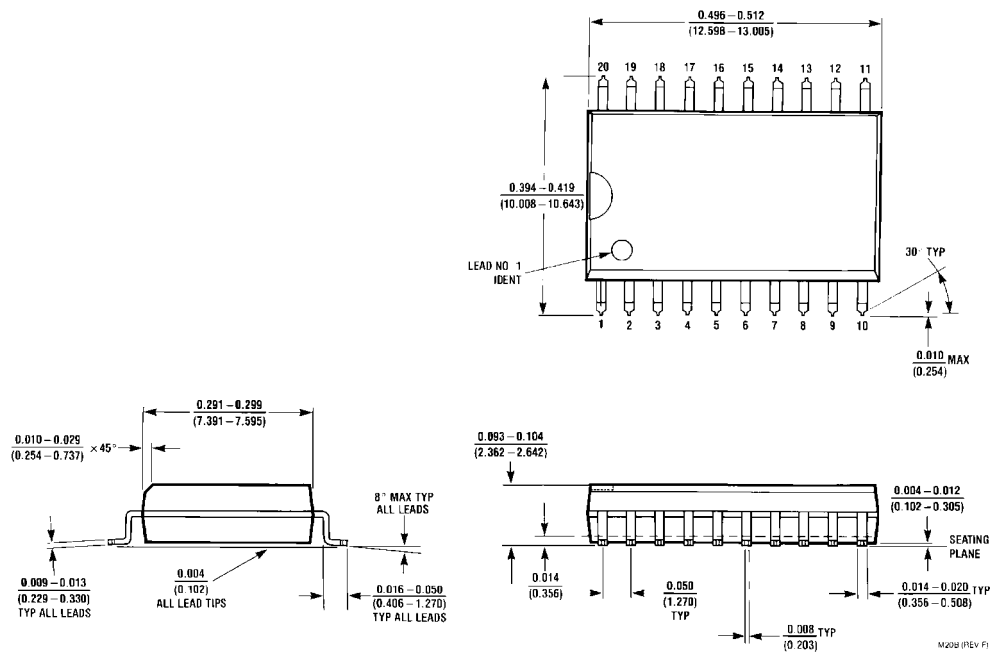
### FSC MLP/DQFN CARRIER TAPE SPECIFICATIONS

### REEL DIMENSIONS inches (millimeters)



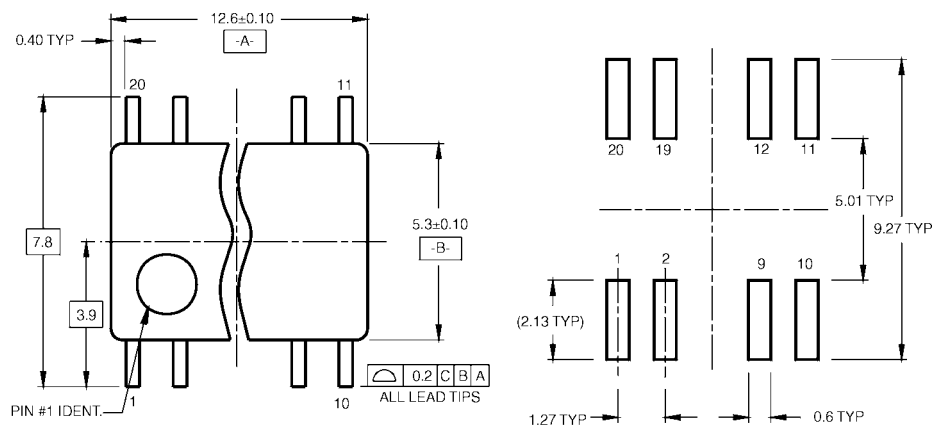
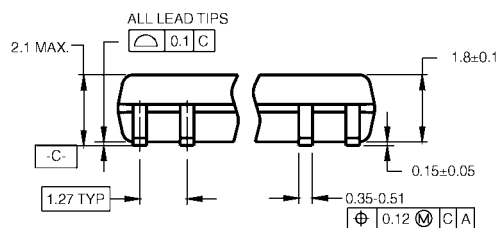
Tape Size	A	B	C	D	N	W1	W2
12 mm	13.0 (330.0)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.488 (12.4)	0.724 (18.4)

# Physical Dimensions inches (millimeters) unless otherwise noted



20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide  
Package Number M20B



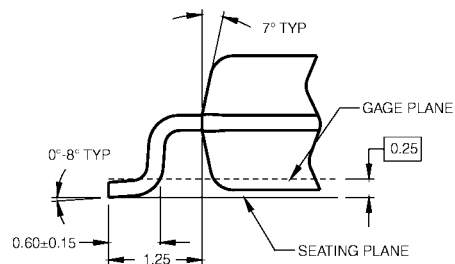
**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)

**LAND PATTERN RECOMMENDATION**


DIMENSIONS ARE IN MILLIMETERS

**NOTES:**

- CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1


**DETAIL A**
**Pb-Free 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
Package Number M20D**



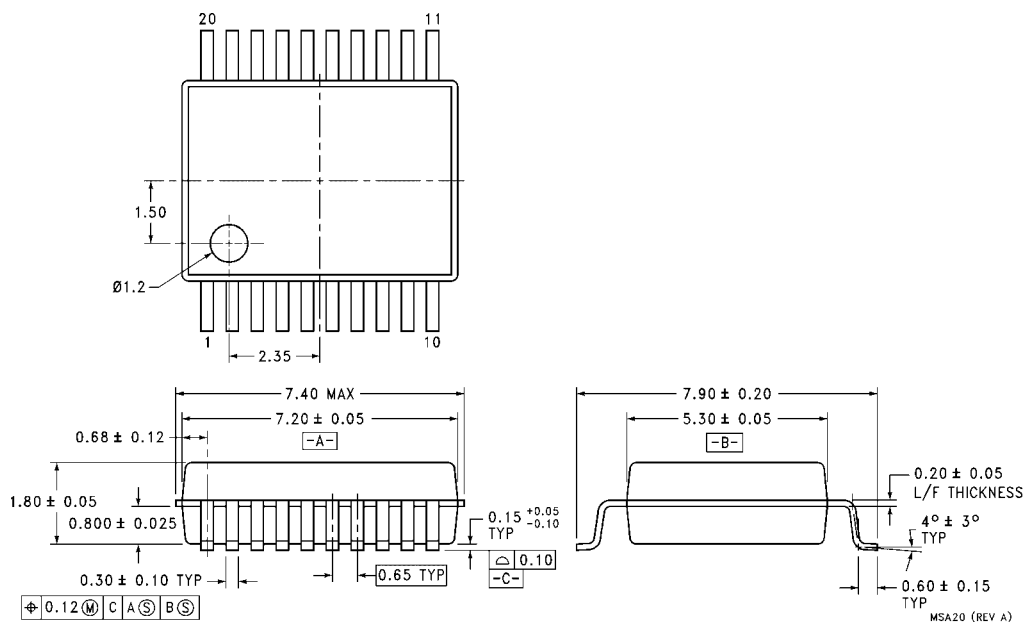
NOTES:

- A. CONFORMS TO JEDEC REGISTRATION  
MO-241, VARIATION AC
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER  
ASME Y14.5M, 1994

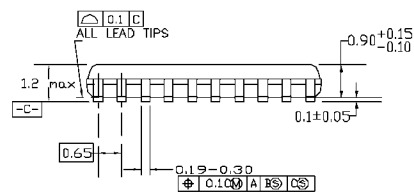
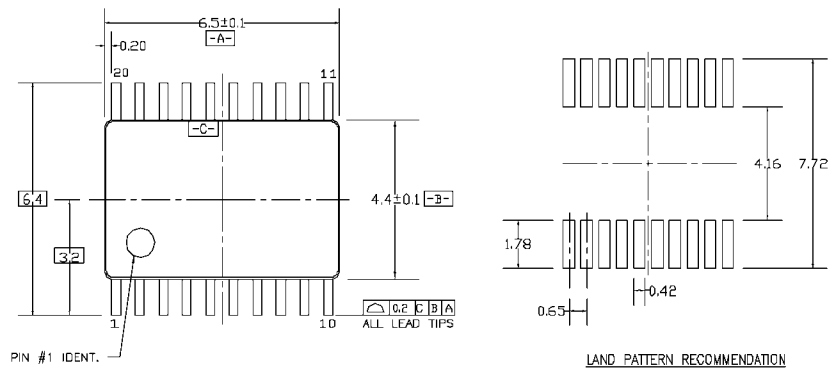
MLP020BrevA

**Pb-Free 20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm  
Package Number MLP020B**

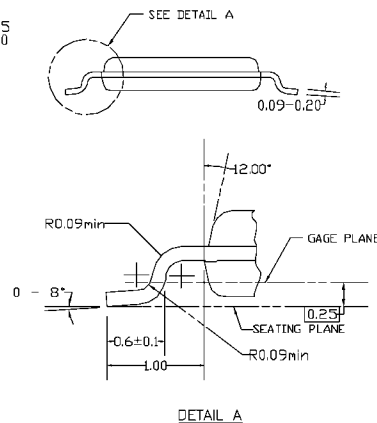
**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide  
Package Number MSA20**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)

DIMENSIONS ARE IN MILLIMETERS



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MB-153, VARIATION AC,  
REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH,  
AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REV D1

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide  
Package Number MTC20**

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